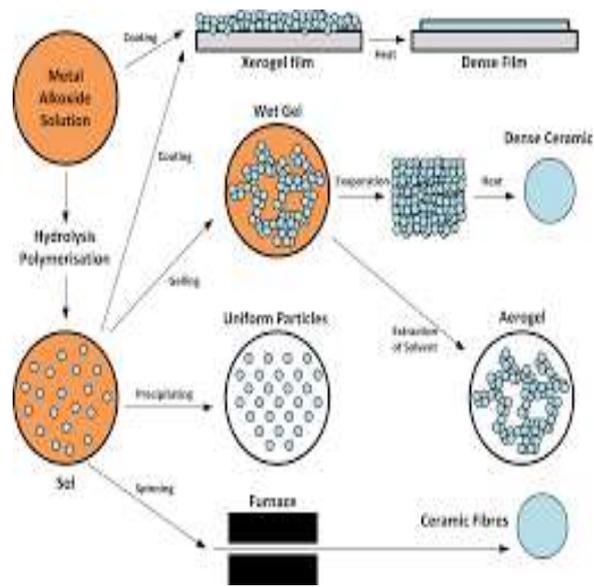


Nano Synthesis Laboratories



Sol Gel Synthesis Unit



Ultra sonication Unit

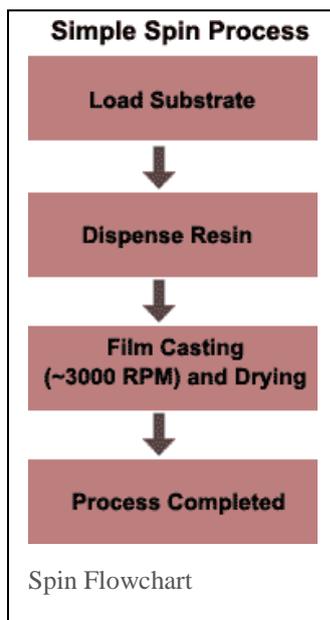
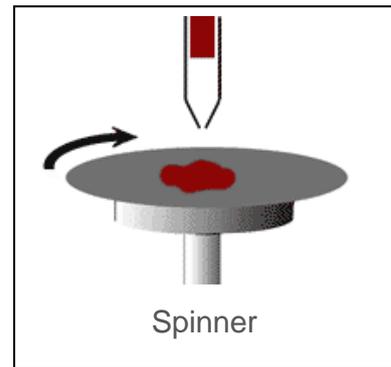


Dip Coating



Spin Coating Unit

Spin coating has been used for several decades as a method for applying thin films. A typical process involves depositing a small puddle of a fluid material onto the center of a substrate and then spinning the substrate at high speed (typically around 3000 rpm). Centripetal acceleration will cause most of the resin to spread to, and eventually off, the edge of the substrate, leaving a thin film of material on the surface. Final film thickness and other properties will depend on the nature of the fluid material (viscosity, drying rate, percent solids, surface tension, etc.) and the parameters chosen for the spin process. Factors such as final rotation speed, acceleration, and fume exhaust affect the properties of the coated films. One of the most important factors in spin coating is repeatability, as subtle variations in the parameters that define a spin-coating process can result in drastic variations in the coated film.



A typical spin process consists of a dispense step in which the resin fluid is deposited onto the substrate surface, a high speed spin step to thin the fluid, and a drying step to eliminate excess solvents from the resulting film. Two common methods of dispense are Static dispense, and Dynamic dispense. Static dispense is simply depositing a small puddle of fluid on or near the center of the substrate. This can range from 1 to 10 cc depending on the viscosity of the fluid and the size of the substrate to be coated. Higher viscosity and or larger substrates typically require a larger puddle to ensure full coverage of the substrate during the high speed spin step. Dynamic dispense is the process of dispensing while the substrate is turning at low speed. A speed of about 500 rpm is commonly used during this step of the process. This serves to spread the fluid over the substrate and can result in less waste of resin material since it is usually not necessary to deposit as much to wet the entire surface of the substrate. This is a particularly advantageous method when the fluid or substrate itself has poor wetting abilities and can eliminate voids that may otherwise form. After the dispense step it is common to accelerate to a relatively high speed to thin the fluid to near its final desired thickness. Typical spin speeds for this step range from 1500-6000 rpm, again depending on the properties of the fluid as well as the substrate. This step can take from 10 seconds to several minutes. The combination of spin speed and time selected for this step will generally define the final film thickness.

In general, higher spin speeds and longer spin times create thinner films. The spin coating process involves a large number of variables that tend to cancel and average out during the spin process and it is best to allow sufficient time for this to occur.